



Sowotech

SOWOTECH

SOWOTECH COMPANY LIMITED

PRODUCT CATALOG

To become the leading intelligent equipment manufacturer in the electronics industry of the world.



PCB Product Series



Thin board
Laminator
FCM30-FREE



Wide board
Laminator
FCM30-PLUS-N
FCM30-PLUS-ND



Large board
Laminator
FCM-43S
FCM-49



Flexible Board
Laminator
RTR-250
RTR 500



Automatic unloader
and loader
SWL(U)R-202K



Automatic unloader
and loader
SWL(U)R-604A



Peeler
PL-26



SWZ-102



SWZ-306

Laminator

Automation

Peeler

Cleaner

Pre-heater

IC-SUBSTRATE Product Series



VacuumLami
nator
V-ONE 11



VacuumLaminat
or
V-ONE200PLUS



Roller Laminator
FCM-30 FREE H



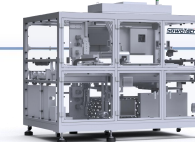
Automatic
unloader and
loader
SWL(U)R-701



Double station
automatic
unloader and
loader SWL(U)R-
651



Six-axis double
station frame
insertion loader and
unloader SWL(U)R-
619L



PL-23



SWZ-102



SWZ-306

Laminator

Automation

Peeler

Cleaner

Pre-heater

Semiconductor product family



BGLaminator
SWAS-600F12



UVLaminator
SWAS-610F12



LCLaminator
SWAS-620F12



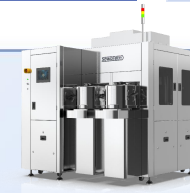
VacuumLaminat
or
SWAS-650F12



Vacuum
Laminator
SV-ONE 11



全自动
Laminator
SFCM-30 FREE



BGPeeler
SWAS-630F12

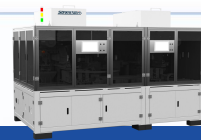
Laminator

Peeler

New energy product series



Double station
high speed laminator
SW-300GS



Double station laminator
SW-300DS



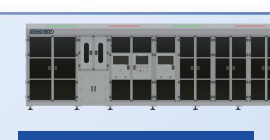
Three-station cutting and
folding machine
SW-300QD



Centrifugal
two seal line
SW-EF160



High speed
die cutting machine
SW-CQ350



Laser slitting
machine



Laser die
cutting machine
SW-JG350

| PCB-Thin board Laminator FCM-30 FREE

Equipment features

The device is an automatic laminator. The overall structure of the main unit does not move, and the entrance and exit plate segments are launched, which is conducive to the stability of the equipment. The pressure structure adopts the back pressure structure, and the pressure uniformity is better, which is suitable for small lines and thin plate coating.

Equipment parameter

Equipment size	L 2150 × H 1985 × W 1670 mm
Working height	950mm-20mm/+50mm
Roll temperature	90-130°Cadjustable (Max150°C)
Board temperature	Min : 300mm (W) x300mm (L) Max : 725mm (W) x 725mm (L) min 0.05-4mm(copper included)
Board thickness	【According to the different thickness of the plate, the machine is divided into 0.05-2.0mm for a group (containing copper) and above 2.0mm for a group (containing copper)】
Roll temperature uniformity (No load&Full load)	No load±3°C
Transport speed	1.0-5.0m/minadjustable



Applicable Processes:Urface Treatment,
Solder Mask, DRY&WET

PCB-Laminator FCM 30-PLUS ND

Equipment description

- Whole boards feeding - centred positioning
- Large roll structure -- wide footprint and long service life
- Servo tension control -- Effective control of film releasing
- Infrared heating -- High thermal efficiency, energy saving and emission reduction.

Technical parameters

Equipment size	L2150 × H2230 × W1680 mm
Working height	950mm-20mm/+50mm
Roll temperature	90-120°C adjustable
Board temperature	Min:300mm(W)×300mm(L) Max:760mm(W)×760mm(L)
Board thickness	0.1-4.0mm(copper included)
Roll temperature uniformity (No load&Full load)	No load±2°C Full load: ±6°C
Transport speed	1.0-5.0m/min adjustable



Applicable Processes: Urface Treatment, Solder Mask, DRY&WET

PCB-Automatic Large board Laminator FCM-43 S

Equipment features

The device is an automatic laminator. The overall structure of the main unit does not move, the input plate segment is launched, and the separation of the outlet plate segment can be tilted design, which is conducive to the stability and handling of the equipment. The pressure structure adopts the back pressure structure, and the pressure uniformity is better, which overcomes the problem of uniform pressure overdeviation caused by the large size and wide width.

Equipment parameter

Equipment Size	L2800 * H2500 * W2250 mm
Working height	1000mm±25mm
Roll temperature	90~120°C adjustable Max : 150°C
Board temperature	Min: 711mm(W)x635mm(L) Max: 1100mm (W) x635mm (L)
Board thickness	Min: 0.4~4mm((copper included))
Roll temperature uniformity (No load&Full load)	No load Ra±3.5°C
Transport speed	1 ~ 5m/min adjustable



Applicable Processes: Urface Treatment, Solder Mask, DRY&WET

PCB-Peeler PL-26

Equipment features

1. The laser sensor automatically detects the width of the board to ensure that the knurling wheel rubs the corner area of the board, reducing the risk of film chips;
2. Tape peeling type , stable and reliable adhesion, easy and quick change of tape and reducing cost in future;
3. Magnetic drive conveyor, no dust;
4. 8 Mispeeled film detection sensors on the top and bottom, covering a wider area;
5. Can be matched with code reading, MES and other information requirements;

Equipment parameter

Equipment Size	2620mm*1700mm*2060mm
Working Height	950~1200±30mm
Board size	350x350mm~730x730mm
Board thickness	0.5~3.2mm
Efficiency	8 Pcs/min
Copper spacing	2-4mm
Mispeeled buffer storage	5片



Applicable processes:
Mylar peeling (Outer layer)

PCB-6 Axis Semi-vertical double stations Loader/Unloader SWL/UR-607

Equipment features

- 1. Dual-station non-stop production, six-axis robot can be selected according to different loads;
- 2. Arm with automatic width adjustment function, according to the characteristics of different process board features of different designs;
- 3. Compatible with a variety of carriers such as flatbed / L-Rack, one-key switching, with code reading NG temporary storage;
- 4. It can be matched with AGV, code reading, MES and other information needs;
- 5. Applicable to high multi-layer, HDI, etc

Equipment parameter:

Equipment Size	2200mm*2150mm*2250mm
Working height	950~1200±30mm
Panel size	300x300mm~630x730mm
Panel thickness	0.05~4.0mm
Efficiency	8 Pcs/min
Power	3Ph 380V 50Hz 5Kw
Air	0.6 Mpa 300NI/min



Applicable Processes:

Inner/Outer Pre-treatment, Inner/Outer clean room, AOI whole process

PCB-4 Axis Semi-vertical double stations Loader/Unloader SWL/UR-202K

Equipment features

- 1. Upper and lower rack exchange, double-station non-stop production, suitable for small space area;
- 2. The arm with automatic width adjustment + clamping jaw function, to adapt to different board sizes;
- 3. 4-axis robot, rotary function can be selectively enabled, with NG temporary storage and automatic complementary Dummy panel;
- 4. It can be matched with AGV, code reading, MES and other information requirements;
- 5. Applicable to high multilayer, HDI, etc.

Equipment parameter:

Equipment Size	3100mm*1500mm*2800mm
Working height	950~1200±30mm
Panel size	300x300mm~630x730mm
Panel thickness	0.05~4.0mm
Efficiency	5 Pcs/min
Power	3Ph 380V 50Hz 5Kw
Air	0.6 Mpa 300NI/min
Equipped with rack	45or 65degree



Applicable Processes:

Electroplating and etc.

PCB-Axis Semi-Vertical with 4 stations integrated loader&unloader SWLR-626

Equipment features

- 1.Four stations non-stop production, with a straight line function, or according to the chain signal to collect or release the board;
- 2. The arm has automatic width adjustment function, MES sends the size of automatic adjustment or manual switching;
- 3. With code reading NG temporary storage;
- 4. It can be matched with AGV, code reading, MES and other information requirements;

Equipment parameter:

Equipment Size	2150mm*2970mm*2600mm
Working height	950~1200±30mm
Panel size	300x300mm~630x730mm
Panel thickness	0.05~4.0mm
Efficiency	8 Pcs/min
Power	3Ph 380V 50Hz 5Kw
Air	0.6 Mpa 300NI/min
Equipped with rack	45or 65degree



Applicable Processes:

Clean room process

PCB-Six-axis Semi-vertical five-station panel unloader SWUR-604A

Equipment features

- 5 workstations continuously materials production, Classify stacking expansion and shrinkage based on interlocking signals
- Classification stacking can use visual recognition of groove markings on the edge of the board
- The arm has automatic width adjustment function. The load of the robot arm can be selected and used according to the weight of the board.

Equipment parameter:

Equipment Size	3200mm*2600mm*2400mm
Working height	950~1200±30mm
Panel size	300x300mm~630x730mm
Panel thickness	0.05~4.0mm
Efficiency	8 Pcs/min
Power	3Ph 380V 50Hz 5Kw
Air	0.6 Mpa 300NI/min
Equipped with rack	45or 65degree



Applicable Processes:
trimming & beveling system

PCB-Flexible board Laminator RTR-250

Equipment features

This device is a roll to roll Flexible board Laminator , the whole machine includes: unwinding part, connection platform, Cleaner, wet pressing or preheating (two options), film placement part, winding part, the structure of the machine is characterized by: the front part of the structure of the film can be opened to the left when the machine is adjusting or cleaning and maintenance of the roll, convenient cleaning and maintenance of the roll and film.

Equipment parameter

Board size	wide≤270
Board thickness	min 0.025-0.1mm
Roll temperature uniformity (No load&Full load)	No load±3℃
Working speed	0.3 ~ 5m/minadjustable
Air source	0.5~0.7MPa 15 L/min
Power source	3-Phase 380V,50/60Hz 10Kw
Net weight	1200 Kg



PCB-Flexible board Laminator RTR-500

Equipment features

This device is a roll to roll Flexible board Laminator , the whole machine includes: unwinding part, connection platform, Cleaner, wet pressing or preheating (two options), film placement part, winding part, the structure of the machine is characterized by: the front part of the structure of the film can be opened to the left when the machine is adjusting or cleaning and maintenance of the roll, convenient cleaning and maintenance of the roll and film

Equipment parameter

Equipment Size	L2050×W1514×H1800mm
Working height	1000±20mm
Transfer speed	0.3-3.0m/minadjustable
Board size	≤520
Board thickness	0.025mm-0.1mm
Deflection correction end face accuracy	±0.5mm
Air source	5-7MPa
Power source	3-Phase 220V, 50/60Hz 10Kw



PCB-Single - and two-row shared loader and unloader SWL(U)-180

Equipment features

- With single and double column sharing function;
- The design of air knife effectively solves the double sheet separation;
- Effectively overcome the problem of thin plate adsorption folding;
- Can be matched with AGV, code reading, MES and other information needs;

Equipment parameter

Equipment Size	1585mm*960mm*2400mm
Working height	950~1200±30mm
Board size	250/260x250mm (双列) 500x600mm (单列)
Board thickness	0.036~2.0mm
Labor rate	8 Pcs/min
Power source	3Ph 380V 50Hz 5Kw
Air source	0.6 Mpa 300NI/min



Applicable process: Vacuum lamination

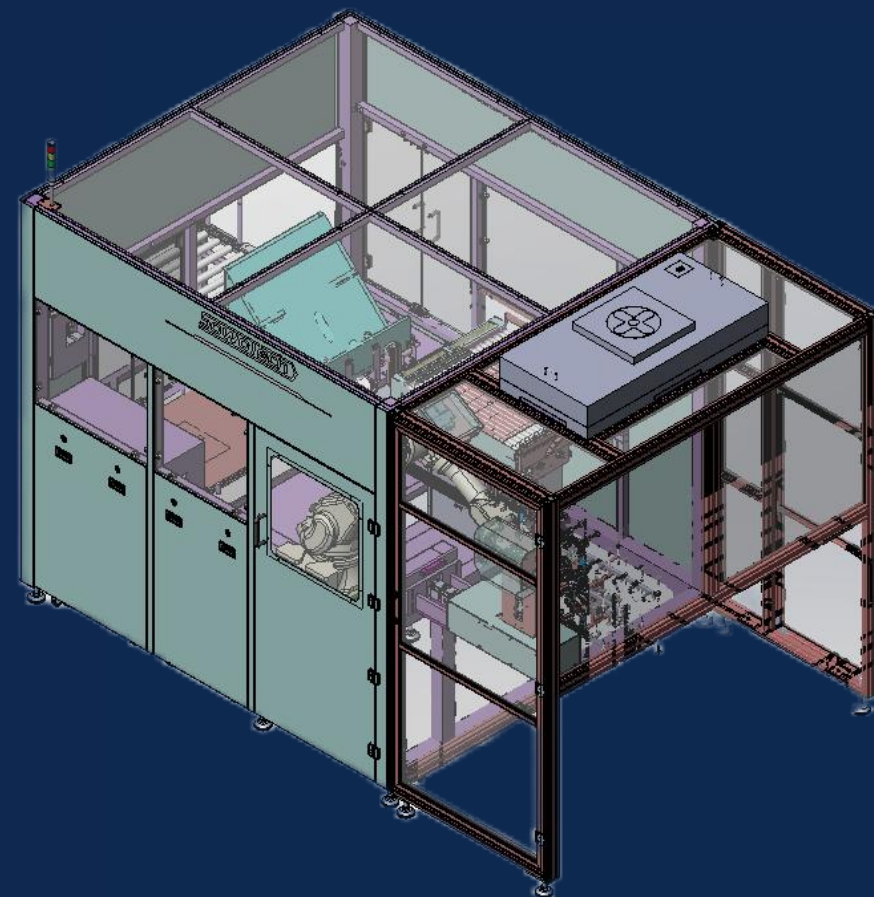
PCB-Automatic loader and unloader SWLR-100

Equipment features

- With automatic turning function, can be selectively enabled;
- Magnetic transmission, HEPA installed on the top of the equipment to keep the equipment clean;
- With single and double column sharing function;
- Can be matched with AGV, code reading, MES and other information needs;

Equipment parameter

Equipment Size	2230mm*2980mm*2480mm
Working height	950±30mm
Board size	250/260x250mm (double column) 500x600mm (single column)
Board thickness	0.036~2.0mm
Labor rate	26S/ surface (13S exposure)
Power source	3Ph 380V 50Hz 4Kw
Air source	0.6 Mpa 300NI/min



Applicable process: Exposure

| IC-Substrate-Vacuum Laminator- V-ONE 11

Equipment description

This equipment is a fully-automatic laminating system that dry film pressing and processing for PCBs, Solder Mask dry film, and ABF film under vacuum conditions.

Technical parameters

Size	6260 × 3235 × 2232mm WH: 1000mm
Weight	about 12T
Board size	Max: 510 × 610 (Max 625×540) Min: 250 × 250 510mm feeding
Board thickness	0.04-2mm warpage less 5mm
Dry film size	Width: 250~540mm 250mm can be done double column
	Dry film roll inner diameter: 3寸(3 inch) Single column with maximum outer diameter of 250mm Double column can fit for up to 200mm
Air conditioner temperature	14~25℃
Film carrier	Width 300~600mm
	Length 1,000m
	Roll diameter 250mm
	Internal diameter about 3.94 inches Thickness 25um (regu



Applicable processes: Pattern transfer, solder resist dry film, line dry film, ABF film

| IC-Substrate-Vacuum Laminator V-ONE 200PLUS

Equipment features

This device is an automatic Laminator device. The overall structure is updated to the form of entering and exiting plates and the main unit is not moving, which is conducive to the accuracy and stability of the film. The outer parts of the machine are fully enclosed with stainless steel mirror to meet the design requirements of high cleanliness. This specification is applicable to HDI and IC carrier plate film processing

Equipment parameter

Board size	MAX:625x725MIN:250x250 625mm
Board thickness	0.05 ((copper included)) -2mm
Dry film specification (pre-attached section)	Width: 250~625mm, 250mm wide can be double columns Dry film drum inner diameter: 3 inches, single row can be installed maximum outer diameter 250mm, double row can be installed maximum 200mm
Air conditioning temperature	14~25℃
Film carrier(Rewind and rewind segments)	Width 300~700mm, length 1000m, roll diameter 250mm, inner diameter 3 inches, thickness 25um (conventional)
Film loading velocity (Rewind and rewind segments)	Maximum 8m/min Positioning accuracy ±3mm



Applicable processes: Pattern transfer, solder resist dry film, line dry film, ABF film

Substrate-Fully automatic roller lamiantor

FCM30-FREE H

Equipment description

The overall structure of the main unit does not move, while entrance conveyor and exit conveyor does for the stability of the equipment. The pressure structure is using the back pressure structure for better pressure uniformity. The whole machine adopts dustproof material, special design, to meet the requirements of the class 100 clean room, suitable for fine lines and thin boards film.

Technical parameters

Equipment size	L 2150 × H 1985 × W 1543mm
Working height	950mm-20mm/+50mm
Roll temperature	90-130°C adjustable (Max 150°C)
Board size	Min : 250mm (W) x250mm (L) Max : 640mm (W) x 640mm (L)
Board thickness	min 0.1-4mm(copper included) three points conveying
Roll temperature uniformity (No load&Full load)	No load±2°C Full load: ±6°C
Working speed	1.0-5.0m/min adjustable



Applicable Processes: Urface Treatment, Solder Mask, DRY&WET

| IC-Substrate-Mylar Peeler PL-23

Equipment description

- Anti-mispeeling residual film detection
- With one key to switch the parameters of the recipe function
- Touch screen contact operation, no dead angle monitoring of the whole machine.
- Support MES and QR code reading
- Three-point contact conveyor, zero-touch pattern area
- Electric cylinder type baffle, automatically adapt to different copper spacing process.

Technical Parameter

Conveyor	Three points contact
Equipment size	515mm(L)x510mm(W)
Height	950±50
Board Thickness	0.5mm-3.0mm
Efficiency	3-4PCS/Min
Tape diameterXwidth	ø76mmX40mm(W)
Weight	1053Kg



Applicable Processes: Sheet type film removal process for IC Substrate and ABF film

| IC-substrate-Magazine Unloader and Loader SWL/U-701

Equipment features

- 1. Fully enclosed design, cleanliness: class 100;
- 2. With fully enclosed Magazine carrier, carrier docking with automatic door opening and closing function;
- 3. Three-point roller, magnetic transmission, the whole process does not touch the board graphic area, can choose to rotate 180 degrees during board exit.
- 4. 2 carriers can be put into the machine at one time, automatic switching, without stopping the material production;
- 5. It can be matched with AGV, code reading, MES and other information technology needs;
- 6. Applicable to FCBGA carrier panels

Equipment parameter

Equipment Size	1853mm*2500mm*2670mm
Working height	950~1200±30mm
Panel size	510x515mm
Panel thickness	0.4~2.5mm
Efficiency	4 Pcs/min
Power	3Ph 380V 50Hz 8Kw
Air	0.6 Mpa 100NI/min
Nos.of stacker	24pcs
Rotation function	0°or 180°available



Applicable processes:
FCBGA Full Process

| IC-substrate-In-Frame insertion Type Loader/unloader SWL/UR-619L

Equipment features

- 1.H-Rack with clamping point function, suitable for 0.05mm thin panel, compatible with a variety of sizes;
- 2. The arm has a clamping jaw stretching function to ensure the flatness of the thin panel, non-contact visual positioning;
- 3. More than one carrier can be put in one time, automatic switching, non-stop production;
- 4. It can be matched with AGV, code reading, MES and other information requirements;
- 5.Applicable to CSP panel carrier

Equipment parameter:

Equipment Size	2300mm*2560mm*2530mm
Working height	950~1200±30mm
Panel size	513x617mm/513x515mmcompatible
Panel thickness	0.05~1.5mm
Efficiency	4 Pcs/min
Power	3Ph 380V 50Hz 7Kw
Air	0.6 Mpa 300NI/min
Nos. of stacker	15pcs /frame
Alignment	CCD



Applicable processes:
Solder Mask,developing, unloader

IC-Substrate-6 axis R fixture loader/unloader SWL/UR-651

Equipment features

- 1.Non-contact curved R/F dual purpose fixture with non-contact between boards in the graphics area;
- 2.The arm has the function of clamping and stretching, non-contact visual positioning;
- 3. With automatic Dummy panel and read code NG temporary storage;
- 4. With AGV, read code, MES and other information needs;
- 5. Applicable to CSP substrate.

Equipment parameter

Equipment Size	3000mm*2200mm*2400mm
Panel size	513x617mm/513x515mmcompatible
Panel thickness	0.05~1.5mm
Effiency	40 s/pcs
Power	3Ph 380V 50Hz 6Kw
Air	0.6 Mpa 300NI/min
Rfixturestacking	3pcs/lot
Positioning	CCD



Applicable processes: VCP loading

Cleaner SWZ-102

Equipment features

- Magnetic drive, the upper and lower are equipped with electrostatic rod;
- Transmission with pull-out function, easy maintenance;
- The thin plate has the function of jumping, and the plate head is pressed down after entering to prevent the card;
- Imported liquid coated roller, long life.

Equipment parameter

Length	258mm
Wide	1320mm
Hight	1250mm
Working height	950~1200±30mm
Board size	300x300mm~630x730mm
Board thickness	0.05~6.0mm
Labor rate	0~10 m/min
Power source	1Ph 220V 50Hz 0.5Kw
Air source	0.6 Mpa 100NI/min



Applicable process: lamination, exposure

Non-contact type pre-heater

SWZ-306

Equipment features

- Non-contact ceramic plate heating, cavity temperature three-stage control;
- Conveying magnetic drive;
- With three point type, drum type and other conveying styles to choose;
- It can meet MES and other information data collection.

Equipment parameter

Length	1200mm
Wide	2370mm
Hight	1662mm
Working height	950~1200±30mm
Board size	300x300mm~630x730mm
Board thickness	0.05~4.0mm
Labor rate	0.5~5.5 m/min
Power source	3Ph 380V 50Hz 14Kw
Set temperature	≤150℃
Exit temperature	50±5℃



Applicable process: lamination,

| BG Tape Laminator SWAS-600F12

Product overview

- High precision fully-automatic tape laminator
- Performs non-contact alignment and tape lamination using a tape tension control function, as well as wafer handling and tape cutting using a multi-joint robot arm, Improves the wafer processing volume per roll of tape a maximum of 16%
- FOUP opener with wafer mapping function is available as standard feature

Technical parameters

Dimensions	Length, width and height: 1350 * 1950 * 1800mm
Wafer size	8inch,12inch
Lamination method	Use roller pressing method for film lamination with adjustable film pressure and tension.
Tape efficiency	30 pcs (film speed 5 mm/s)—70 pcs (film speed 60 mm/s)



| Wafer Mounter SWAS-610F12

Product overview

- Fully-automatic wafer mounter suited for ultra-thin wafer manufacturing, with the following functions: · UV irradiation to BG Tape · Alignment · Wafer mounting · BG Tape peeling
- Corresponds to DBG process
- Prevents wafer damage by reducing wafer handling frequency down to 4 times "stand-alone," and 2 times "in-line."

Technical parameter

Dimensions	Length, width and height: 3128 * 2770 * 1800mm
Wafer size	8 inches & 12 inches
Capacity	About 25 to 30 pieces of work per hour
Laminating method	Use roller pressing method for film lamination with adjustable film pressure and tension.



| LC Tape Lamination SWAS-620F12

Product overview

- Fully-automatic LC Tape laminator which laminates LC Tape to wafer backside after back grinding
- -Performs the following functions: · Wafer alignment · LC Tape pre-cutting · LC Tape lamination · Release liner peeling

Technical parameter

Dimensions	Length, width and height: 1950 * 2050 * 1800mm
Wafer size	8inch , 12inch
Weight of equipment	1500KG
Lamination efficiency	And 25-30 tablets / hour



| BG Tape Remover SWAS-630F12

Product overview

- Fully-automatic BG Tape remover for single wafer.
- After alignment, UV is irradiated when necessary, and back grinding tape is removed by attaching heat seal on the periphery of the wafer, fixed with heater.

Technical parameter

Equipment Size	Length * width * height: 1930mm * 1790mm * 1788mm (excluding signal light)
WPH	15~30 pieces (different film tearing speed for different products)
Wafer size	8 inches , 12 inches
Buckling	≤6mm



Fully Automatic Laminator SFCM-30

FREE

Product overview

The overall structure of the main unit is not moving, the entry and exit of the plate section, is conducive to the stability of the equipment, the pressure structure adopts back pressure structure, pressure uniformity is better, the whole machine uses dust material, dust special design, to meet the requirements of the clean room, suitable for fine lines and thin sheet film

Technical parameter

Equipment Size	L 2150 × H 1985 × W 1543mm
Working Height	950mm-20mm/+50mm
Pressure rumble temperature	90-130°C adjustable (up to 150°C)
Plate size	Min : 250mm (W) x 250mm (L) M ax : 640mm (W) x 640mm (L)
thickness of slab	Min 0.1-4mm (including copper) three-point delivery
Reroll temperature uniformity control (No-load & full-load)	No-load ± 2°Cloaded to capacity:±6°C
working speed	1.0-5.0m/min Adjustable



Fully Automatic Vacuum Lamination system SV-ONE 11

Product overview

- Three-point Conveying: The whole machine adopts three - point conveying, which reduces the contact area between the plate surface and the driving roller and the friction.
- IR Heating: The heater are fixed, no rotating and friction, which saves energy and reduces emission.
- Back Pressure Structure Back-pressure film press, no mechanical disassembly for laminating roll replacement.
- Feeding and Dust Extraction Feeding drive with magnetic drive and dust extraction design.

Technical parameter

Equipment Size	6260 × 3235 × 2232mm WH : 1000mm
Equipment Weight	About 12T
Panel size	510 610 (510mm side board)
Panel thickness	0.04-2mm warping is less than 5mm
Air supply	≥0.5 Mpa 50 L/min 2 φ 12 trachea
Flattening accuracy	≤15um (remove the flattening steel plate and buffer material)
Power supply	AC380V Three-phase five-wires 50 Hz 50KW



New energy-Duplex Chip Lamination Machine SW-300DS

Equipment features

This equipment is used for Z-shaped lamination of positive and negative electrode plate of lithium ion battery cells, and integrates the functions of electrode feeding, diaphragm rolling, CCD / mechanical positioning, tension correction, CCD detection, automatic lamination, automatic finishing roll, automatic adhesive, automatic unloading and so on.

Technical parameter

Overlay accuracy	$\pm 0.3\text{mm}$
Yield	$\geq 99.5\%$
Cleanliness	Ten thousand level
Efficiency	$\geq 100\text{PCS}$



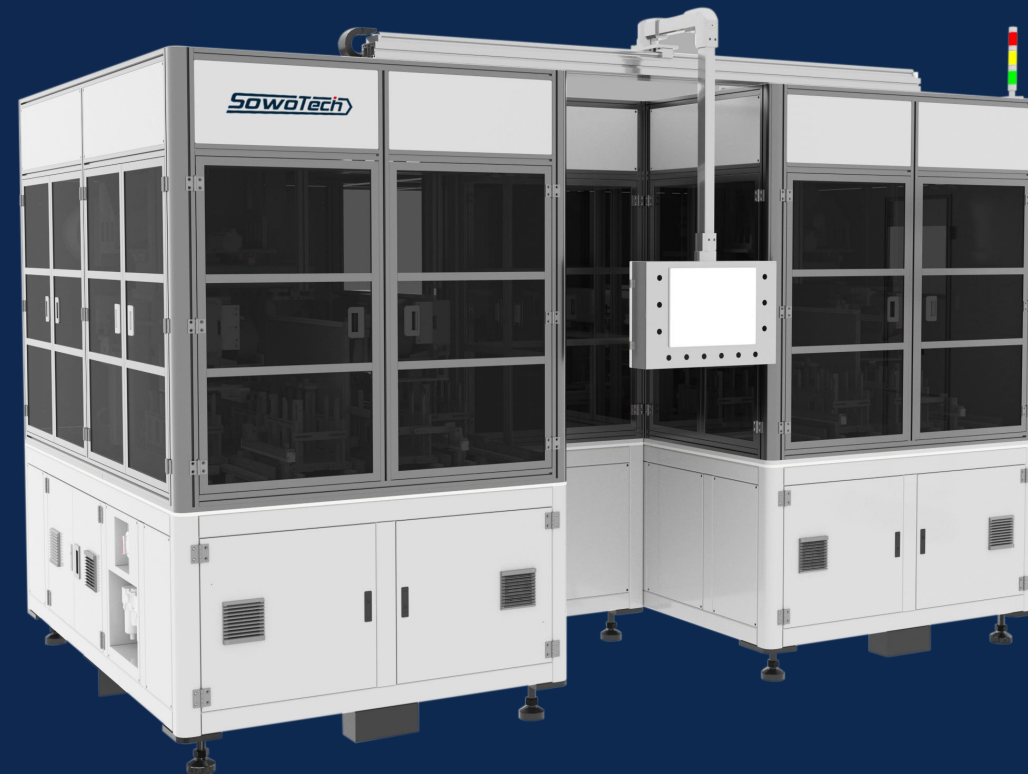
New energy-Dual-station High-speed Lammachine SW-300GS

Product overview

This equipment is used for Z-shaped lamination of positive and negative electrode plate of lithium ion battery cells, and integrates the functions of electrode feeding, diaphragm rolling, CCD / mechanical positioning, tension correction, CCD detection, automatic lamination, automatic finishing roll, automatic adhesive, automatic unloading and so on

Technical parameter

Overlay accuracy	$\pm 0.3\text{mm}$
Yield	$\geq 99.5\%$
Tension fluctuations	$\leq 5\%$
Cleanliness	万级 Ten thousand level
Efficiency	$\geq 200\text{PCS}$



New energy-three-site machine SW-300 QD

Product overview

This equipment is used for cutting positive and negative electrode plates and Z-shaped lamination of lithium ion battery cells, which integrates the functions of pole roll, punching, cutting, lamination, tail roll, adhesive, adhesive, hot pressing and feeding, to achieve less humanization, strong compatibility, high degree of automation, and can be cut and folded

Technical parameter

- Lamination accuracy: $\pm 0.3\text{mm}$
- Yield: $\geq 99.5\%$
- Tension fluctuations $\leq 5\%$
- Cleanliness: ten thousand level
- Lamination efficiency: $\geq 480\text{PCS}$
- Cutting accuracy: $\pm 0.2\text{mm}$
- Ar accuracy: $\leq 10\mu$



New energy-centrifugal secondary sealing line SW-EF160

Product overview

This equipment is used for the production of square soft pack lithium ion battery testing, two sealing pumping, folding, weighing and other processes. This equipment has automatic loading (cartridge, bullet clip, water wheel, plastic box or manual loading mode optional), voltage test, chamber positioning, chamber weighing, vacuum packaging, air cutting bag, fine sealing, scanning code, edge voltage test, cutting and folding edge (single and double folding compatible), after weighing, cutting sorting and other functions. The equipment adopts a modular structure, and can be freely selected and matched according to customer needs.

Technical parameter

- Standard variance of residual fluid volume δ 0.04
- $< 0.05g$ Centrifugal extraction, cell fluid loss $< 0.05g$
- thickness accuracy is $\pm 0.005mm$, CPK 1.33
- Capacity of 18 PPM
- Capacity of 18 PPM
- The rate is $\geq 98\%$



New energy-high-speed die-cutting machine SW-CQ350

Product overview

For power lithium battery positive, negative pole sheet forming, have active roll, multilevel correction system to roll the process of automatic correction, and through the tension control system control roll tension, hardware die cutting molding, CCD defect detection, size detection, dust removal system, vacuum belt conveying pole, bad product automatically eliminate, qualified product automatic collection, and other functions

Technical parameter

Cutting accuracy	$\pm 0.2\text{mm}$
Burr accuracy	$\leq 10\mu\text{m}$
Tension fluctuations	$\leq 5\%$
Cleanliness	Ten thousand level
Efficiency	280PCS



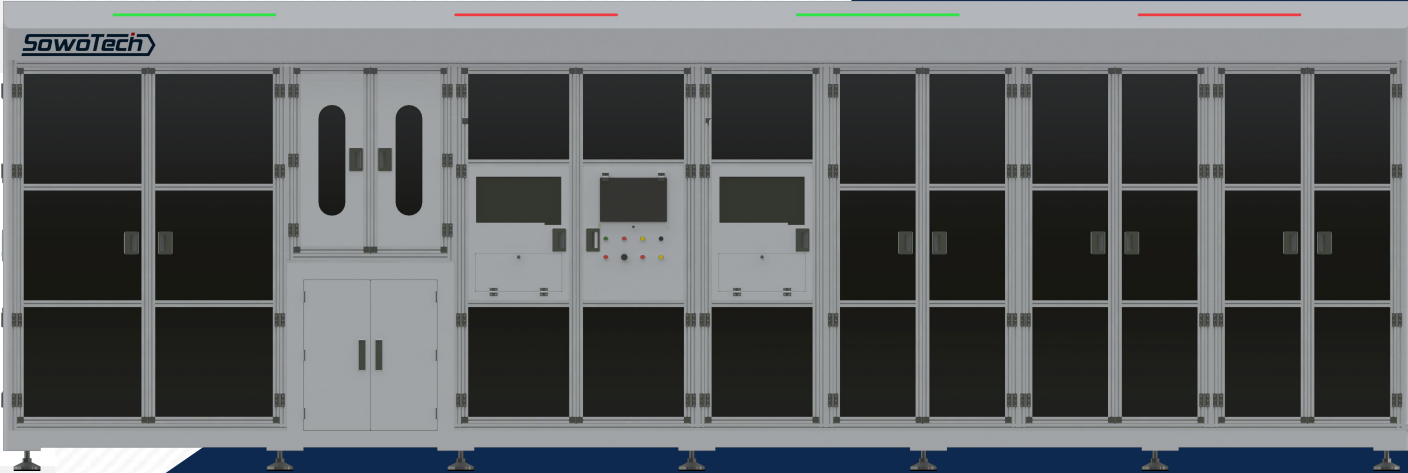
New energy-laser division and cutting integrated machine

Product overview

Equipment has the functions of automatic winding, multilevel correction, tension control, pole ear rolling, pole ear cutting, multistage dust removal, pole piece defect detection, pole ear size and width detection of pole slice, pole slice cutting, bad labeling, material roll smoothing, automatic winding and so on

Technical parameter

Extra-chip delivery speed	$\geq 130\text{m/min}$
Heat-affected zone	$\leq 70\mu\text{m}$
rag	$\leq 15\mu\text{m}$
Desection accuracy of pole chip	$\leq \pm 0.1\text{mm}$
Extra-chip volume accuracy	$\leq \pm 0.5\text{mm}$
Tension fluctuations	$\leq 5\%$
A premium rate	$\geq 99.5\%$
Utilization rate	$\geq 95\%$



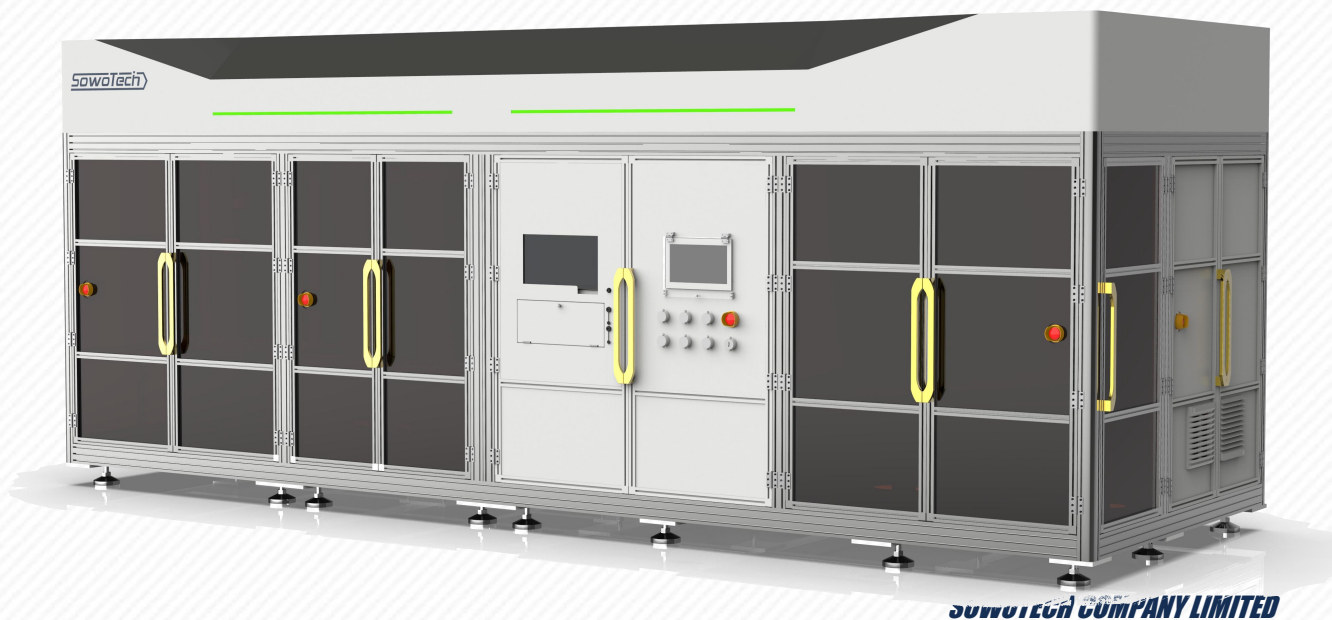
New energy-laser die-cutting machine SW-JG 350

Product overview

For power lithium battery positive, negative pole sheet forming, have active roll, multilevel correction system to roll the process of automatic correction, and through the tension control system control roll tension, hardware die cutting molding, CCD defect detection, size detection, dust removal system, vacuum belt conveying pole, bad product automatically eliminate, qualified product automatic collection, and other functions

Technical parameter

Cutting accuracy	$\pm 0.2\text{mm}$
Burr accuracy	$\leq 10\mu\text{m}$
Tension fluctuations	$\leq 5\%$
Cleanliness	Ten thousand level
The lamination efficiency	280PCS



Solar- Proximity exposure machine

PMD100

Equipment features

- The capacity of single machine reaches 8000 pieces /H
- Line width resolution 35um/35um, resolution accuracy $\pm 10\%$
- High precision optical system with proximity, no need for expensive projection lens, simple maintenance, stable and reliable, cost-effective
- Up to 230x120mm large-format exposure area, silicon one-time exposure is completed, no need to splice graphics, stable and reliable
- High precision machinery and motion control technology for safe mass production with minimal mask gap
- With constant temperature and humidity system, maintain the constant temperature environment of $\pm 0.5^{\circ}\text{C}$ equipment to ensure stable operation
- Intelligent software design, real-time monitoring of equipment

Equipment parameter

Equipment Size	2900*2300*2270mm
Working height	960 $\pm$ 20mm
Applicable substrate size	Photovoltaic cell G12 half piece (210x105mm)
Board thickness	100~150 μm
Alignment accuracy	Edge alignment $\pm 50\mu\text{m}$, mark alignment $\pm 20\mu\text{m}$
Labor rate	8000 pieces @G12 half piece (0.9s/2pcs half piece)



Application process: photovoltaic cell grid line graphic exposure

THANKS

CONTACT US



Tel
400-885-0998



E-mail
marketing@sowotech.com



Web
www.sowotech.com



Add
Building 13, No.2 Xingye Road, Songshan Lake
Park, Dongguan City, Guangdong Province



Office account